

Special Issue

Advanced Deep Learning Methods for Large-Scale Food Distribution

Message from the Guest Editor

This Special Issue welcomes paper submissions from all areas of deep learning applications, with a special focus on the research articles showing the development of advanced bio-inspired deep solutions and algorithms for addressing the main issues of large-scale food distribution (LSFD). We strongly encourage the submission of papers that explore new research perspectives in different areas of LSFD including, but not limited to, deep learning for shelf availability monitoring in retail stores, supervised deep solutions for shelf availability forecasting retail stores, unsupervised approaches and reinforcement learning for shelf availability forecasting retail stores, retail sentiment analysis, etc.

Guest Editor

Prof. Dr. Francesco Rundo

STMicronics, ADG R&D Power and Discretes Division, Artificial Intelligence Team, Catania, Italy

Deadline for manuscript submissions

closed (25 September 2022)



Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.5



mdpi.com/si/94979

Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
appls@mdpi.com

[mdpi.com/journal/
appls](https://mdpi.com/journal/appls)





Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.5



[mdpi.com/journal/
applsci](https://mdpi.com/journal/applsci)



About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

Author Benefits

Open Access:

free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:

indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, CAPlus / SciFinder, and other databases.

Journal Rank:

JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)